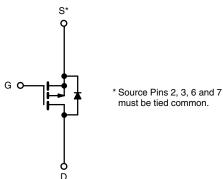


F7703-VB Datasheet Dual P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R_{DS(on)} (Ω)	I _D (A) ^{d, e}	Q _g (Typ.)		
- 30	0.016 at V _{GS} = - 10 V	- 9.5	15 nC		
- 30	0.020 at V _{GS} = - 4.5 V	- 8.0	15110		

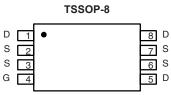


FEATURES

- Halogen-free
- Trench Power MOSFET
- 100 % UIS Tested

APPLICATIONS

- Load Switches
 - Notebook PCs
 - Desktop PCs
 - Game Stations



Top View

Pb-free RoHS

COMPLIANT

P-Channel	MOSEET
i onumer	

ABSOLUTE MAXIMUM RATINGS T	$A = 25 \ ^{\circ}C$, unless othe	erwise noted		
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	- 30	V	
Gate-Source Voltage		V _{GS}	± 20	v
	T _C = 25 °C		- 9.5 ^e	
Continuous Drain Current ($T_1 = 150 \text{ °C}$)	T _C = 70 °C		- 8.0 ^e	
Continuous Drain Current (1) = 150°C)	T _A = 25 °C	I _D	- 8.3 ^{a, b}	
	T _A = 70 °C		- 7.9 ^{a, b}	Α
Pulsed Drain Current	I _{DM}	- 32 ^e	A	
	T _C = 25 °C		- 4.1	
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	- 2.0 ^{a, b}	
Avalanche Current		I _{AS}	- 20	
Single-Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	20	mJ
	T _C = 25 °C		5.0	
Marian Dissingtion	T _C = 70 °C		3.2	
Maximum Power Dissipation	T _A = 25 °C	P _D	2.5 ^{a, b}	W
	T _A = 70 °C		1.6 ^{a, b}	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	38	50	°C/W
Maximum Junction-to-Foot	Steady State	R _{thJF}	20	25	0/00

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. t = 10 s.

c. Maximum under Steady State conditions is 85 °C/W.

d. Based on T_C = 25 °C.

e. Limited by package.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static					1		
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA	- 30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$			- 31		200	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA		4.5		mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$	- 1.0		- 3.0	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zana Olata Maltana Daria Orana di	-	$V_{DS} = -30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			- 1		
Zero Gate Voltage Drain Current	IDSS	V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 55 °C			- 5	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge -10 \text{ V}, \text{ V}_{GS} = -10 \text{ V}$	- 30			Α	
		V _{GS} = - 10 V, I _D = - 7.3 A		0.016		Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 6.2 A		0.020			
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 9.1 A		23		S	
Dynamic ^b					<u> </u>		
Input Capacitance	C _{iss}			1350			
Output Capacitance	C _{oss}	V _{DS} = - 15 V, V _{GS} = 0 V, f = 1 MHz		215		pF	
Reverse Transfer Capacitance	C _{rss}			185		-	
Tetal Oats Ohanna	0	V _{DS} = - 15 V, V _{GS} = - 10 V, I _D = - 9.1 A		32	50	-	
Total Gate Charge	Q_g			15	25		
Gate-Source Charge	Q _{gs}	V _{DS} = - 15 V, V _{GS} = - 4.5 V, I _D = - 9.1 A		4		nC	
Gate-Drain Charge	Q _{gd}			7.5			
Gate Resistance	R _g	f = 1 MHz		5.8		Ω	
Turn-On Delay Time	t _{d(on)}			10	15		
Rise Time	t _r	V_{DD} = - 15 V, R _L = 15 Ω		8	15		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 1 A, V_{GEN} = - 10 V, R_g = 1 Ω		45	70		
Fall Time	t _f			12	25		
Turn-On Delay Time	t _{d(on)}			42	70	ns	
Rise Time	t _r	V_{DD} = - 15 V, R _L = 15 Ω		35	60	-	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 1 A, V_{GEN} = - 4.5 V, R_g = 1 Ω		40	70		
Fall Time	t _f			16	30		
Drain-Source Body Diode Characterist	ics						
Continous Source-Drain Diode Current	۱ _s	T _C = 25 °C			- 4.1	٨	
Pulse Diode Forward Current	I _{SM}				- 32	A	
Body Diode Voltage	V _{SD}	I _S = - 2 A, V _{GS} = 0 V		- 0.75	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			34	60	ns	
Body Diode Reverse Recovery Charge	Q _{rr}			22	40	nC	
Reverse Recovery Fall Time	t _a	I _F = - 2 A, dl/dt = 100 A/μs, T _J = 25 °C		11			
Reverse Recovery Rise Time	t _b			23		ns	

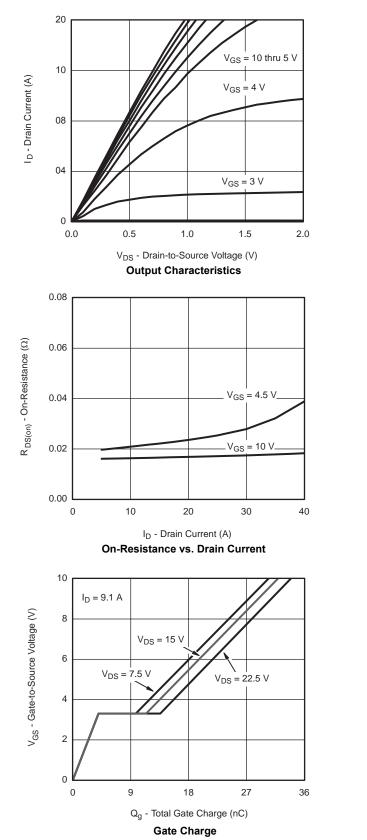
Notes:

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

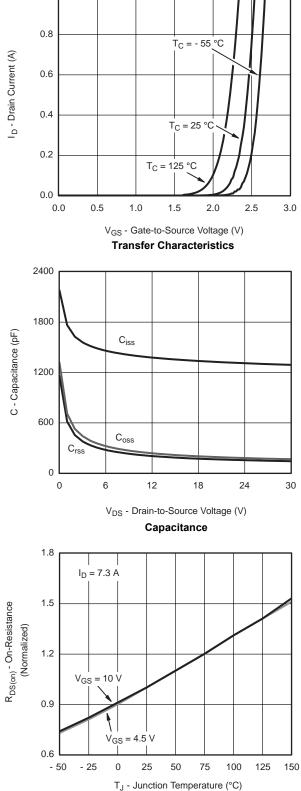
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





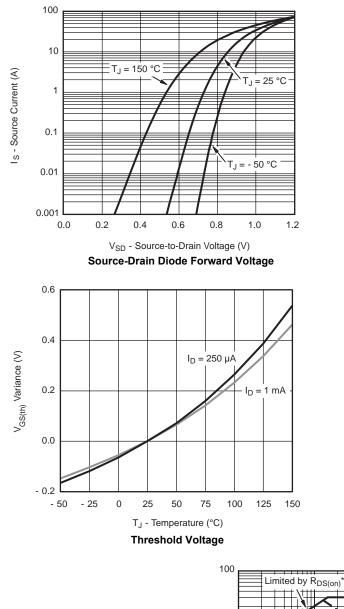




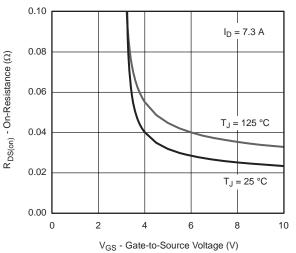
On-Resistance vs. Junction Temperature

1.0

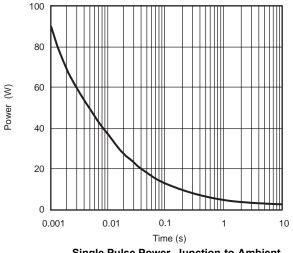




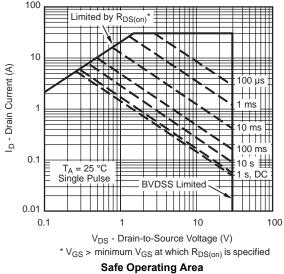
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



On-Resistance vs. Gate-to-Source Voltage

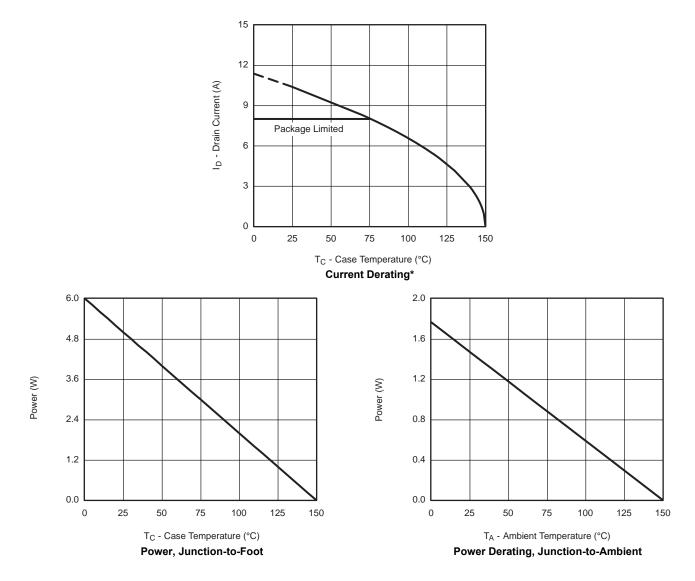


Single Pulse Power, Junction-to-Ambient





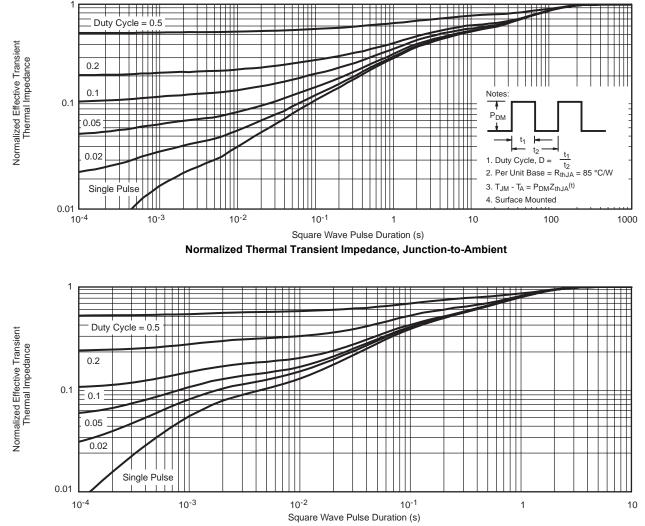
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





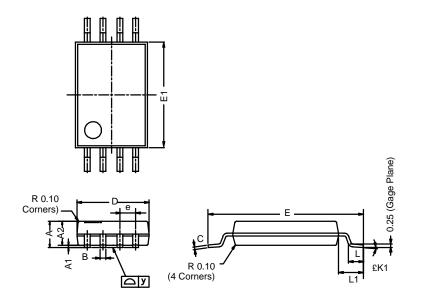


Normalized Thermal Transient Impedance, Junction-to-Foot



TSSOP: 8-LEAD

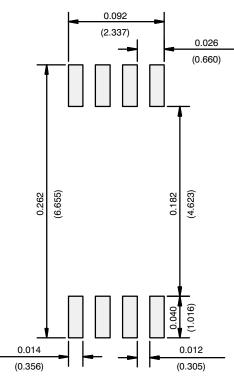
JEDEC Part Number: MO-153



	MILLIMETERS				
Dim	Min	Nom	Max		
Α	-	-	1.20		
A 1	0.05	0.10	0.15		
A ₂	0.80	1.00	1.05		
В	0.19	0.28	0.30		
С	-	0.127	-		
D	2.90	3.00	3.10		
Е	6.20	6.40	6.60		
E ₁	4.30	4.40	4.50		
е	-	0.65	-		
L	0.45	0.60	0.75		
L ₁	0.90	1.00	1.10		
Y	-	-	0.10		
£ K1	0°	3°	6°		
ECN: S-03946—Rev. G, 09-Jul-01 DWG: 5844					



RECOMMENDED MINIMUM PADS FOR TSSOP-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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